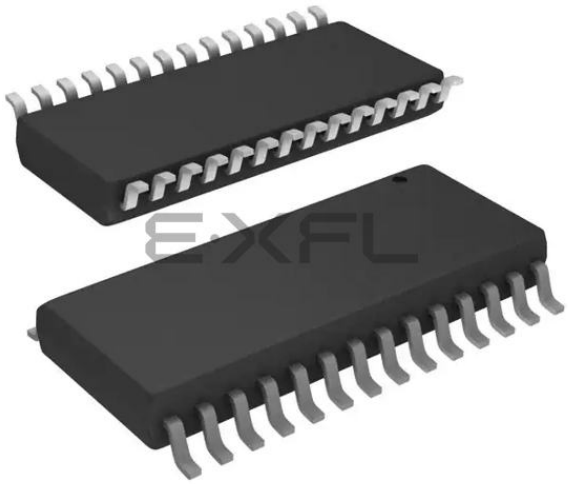

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2420-i-so

TABLE 1-2: PIC18F2420/2520 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	SPDIP, SOIC	QFN			
					PORTC is a bidirectional I/O port.
RC0/T1OSO/T13CKI	11	8			
RC0			I/O	ST	Digital I/O.
T1OSO			O	—	Timer1 oscillator output.
T13CKI			I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2	12	9			
RC1			I/O	ST	Digital I/O.
T1OSI			I	Analog	Timer1 oscillator input.
CCP2(2)			I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
RC2/CCP1	13	10			
RC2			I/O	ST	Digital I/O.
CCP1			I/O	ST	Capture 1 input/Compare 1 output/PWM1 output.
RC3/SCK/SCL	14	11			
RC3			I/O	ST	Digital I/O.
SCK			I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL			I/O	ST	Synchronous serial clock input/output for I^2C™ mode.
RC4/SDI/SDA	15	12			
RC4			I/O	ST	Digital I/O.
SDI			I	ST	SPI data in.
SDA			I/O	ST	I^2C data I/O.
RC5/SDO	16	13			
RC5			I/O	ST	Digital I/O.
SDO			O	—	SPI data out.
RC6/TX/CK	17	14			
RC6			I/O	ST	Digital I/O.
TX			O	—	EUSART asynchronous transmit.
CK			I/O	ST	EUSART synchronous clock (see related RX/DT).
RC7/RX/DT	18	15			
RC7			I/O	ST	Digital I/O.
RX			I	ST	EUSART asynchronous receive.
DT			I/O	ST	EUSART synchronous data (see related TX/CK).
RE3	—	—	—	—	See $\overline{MCLR}$/VPP/RE3 pin.
VSS	8, 19	5, 16	P	—	Ground reference for logic and I/O pins.
VDD	20	17	P	—	Positive supply for logic and I/O pins.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

4.5 Device Reset Timers

PIC18F2420/2520/4420/4520 devices incorporate three separate on-chip timers that help regulate the Power-on Reset process. Their main function is to ensure that the device clock is stable before code is executed. These timers are:

- Power-up Timer (PWRT)
- Oscillator Start-up Timer (OST)
- PLL Lock Time-out

4.5.1 POWER-UP TIMER (PWRT)

The Power-up Timer (PWRT) of PIC18F2420/2520/4420/4520 devices is an 11-bit counter which uses the INTRC source as the clock input. This yields an approximate time interval of 2048 x 32 µs = 65.6 ms. While the PWRT is counting, the device is held in Reset.

The power-up time delay depends on the INTRC clock and will vary from chip to chip due to temperature and process variation. See DC parameter 33 for details.

The PWRT is enabled by clearing the $\overline{\text{PWRTEN}}$ Configuration bit.

4.5.2 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter 33). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP, HS and HSPLL modes and only on Power-on Reset, or on exit from most power-managed modes.

4.5.3 PLL LOCK TIME-OUT

With the PLL enabled in its PLL mode, the time-out sequence following a Power-on Reset is slightly different from other oscillator modes. A separate timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (T_{PLL}) is typically 2 ms and follows the oscillator start-up time-out.

4.5.4 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows:

1. After the POR pulse has cleared, PWRT time-out is invoked (if enabled).
2. Then, the OST is activated.

The total time-out will vary based on oscillator configuration and the status of the PWRT. Figure 4-3, Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7 all depict time-out sequences on power-up, with the Power-up Timer enabled and the device operating in HS Oscillator mode. Figure 4-3 through Figure 4-6 also apply to devices operating in XT or LP modes. For devices in RC mode and with the PWRT disabled, on the other hand, there will be no time-out at all.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, all time-outs will expire. Bringing $\overline{\text{MCLR}}$ high will begin execution immediately (Figure 4-5). This is useful for testing purposes or to synchronize more than one PIC18FXXXX device operating in parallel.

TABLE 4-2: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up[2] and Brown-out		Exit from Power-Managed Mode
	$\overline{\text{PWRTEN}}$ = 0	$\overline{\text{PWRTEN}}$ = 1	
HSPLL	66 ms[1] + 1024 TOSC + 2 ms[2]	1024 TOSC + 2 ms[2]	1024 TOSC + 2 ms[2]
HS, XT, LP	66 ms[1] + 1024 TOSC	1024 TOSC	1024 TOSC
EC, ECIO	66 ms[1]	—	—
RC, RCIO	66 ms[1]	—	—
INTIO1, INTIO2	66 ms[1]	—	—

Note 1: 66 ms (65.5 ms) is the nominal Power-up Timer (PWRT) delay.
2: 2 ms is the nominal time required for the PLL to lock.

5.1.1 PROGRAM COUNTER

The Program Counter (PC) specifies the address of the instruction to fetch for execution. The PC is 21 bits wide and is contained in three separate 8-bit registers. The low byte, known as the PCL register, is both readable and writable. The high byte, or PCH register, contains the PC<15:8> bits; it is not directly readable or writable. Updates to the PCH register are performed through the PCLATH register. The upper byte is called PCU. This register contains the PC<20:16> bits; it is also not directly readable or writable. Updates to the PCU register are performed through the PCLATU register.

The contents of PCLATH and PCLATU are transferred to the program counter by any operation that writes PCL. Similarly, the upper two bytes of the program counter are transferred to PCLATH and PCLATU by an operation that reads PCL. This is useful for computed offsets to the PC (see **Section 5.1.4.1 "Computed GOTO"**).

The PC addresses bytes in the program memory. To prevent the PC from becoming misaligned with word instructions, the Least Significant bit of PCL is fixed to a value of '0'. The PC increments by 2 to address sequential instructions in the program memory.

The CALL, RCALL, GOTO and program branch instructions write to the program counter directly. For these instructions, the contents of PCLATH and PCLATU are not transferred to the program counter.

5.1.2 RETURN ADDRESS STACK

The return address stack allows any combination of up to 31 program calls and interrupts to occur. The PC is pushed onto the stack when a CALL or RCALL instruction is executed or an interrupt is Acknowledged. The PC value is pulled off the stack on a RETURN, RETLW or a RETFIE instruction. PCLATU and PCLATH are not affected by any of the RETURN or CALL instructions.

The stack operates as a 31-word by 21-bit RAM and a 5-bit Stack Pointer, STKPTR. The stack space is not part of either program or data space. The Stack Pointer is readable and writable and the address on the top of the stack is readable and writable through the Top-of-Stack (TOS) Special Function Registers. Data can also be pushed to, or popped from the stack, using these registers.

A CALL type instruction causes a push onto the stack; the Stack Pointer is first incremented and the location pointed to by the Stack Pointer is written with the contents of the PC (already pointing to the instruction following the CALL). A RETURN type instruction causes a pop from the stack; the contents of the location pointed to by the STKPTR are transferred to the PC and then the Stack Pointer is decremented.

The Stack Pointer is initialized to '00000' after all Resets. There is no RAM associated with the location corresponding to a Stack Pointer value of '00000'; this is only a Reset value. Status bits indicate if the stack is full, or has overflowed or underflowed.

5.1.2.1 Top-of-Stack Access

Only the top of the return address stack (TOS) is readable and writable. A set of three registers, TOSU:TOSH:TOSL, hold the contents of the stack location pointed to by the STKPTR register (Figure 5-2). This allows users to implement a software stack if necessary. After a CALL, RCALL or interrupt, the software can read the pushed value by reading the TOSU:TOSH:TOSL registers. These values can be placed on a user-defined software stack. At return time, the software can return these values to TOSU:TOSH:TOSL and do a return.

The user must disable the global interrupt enable bits while accessing the stack to prevent inadvertent stack corruption.

FIGURE 5-2: RETURN ADDRESS STACK AND ASSOCIATED REGISTERS

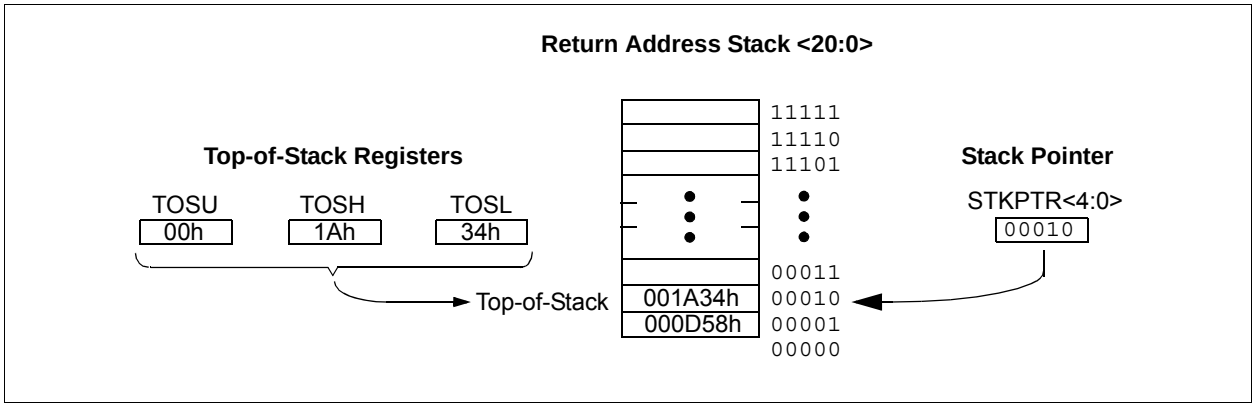
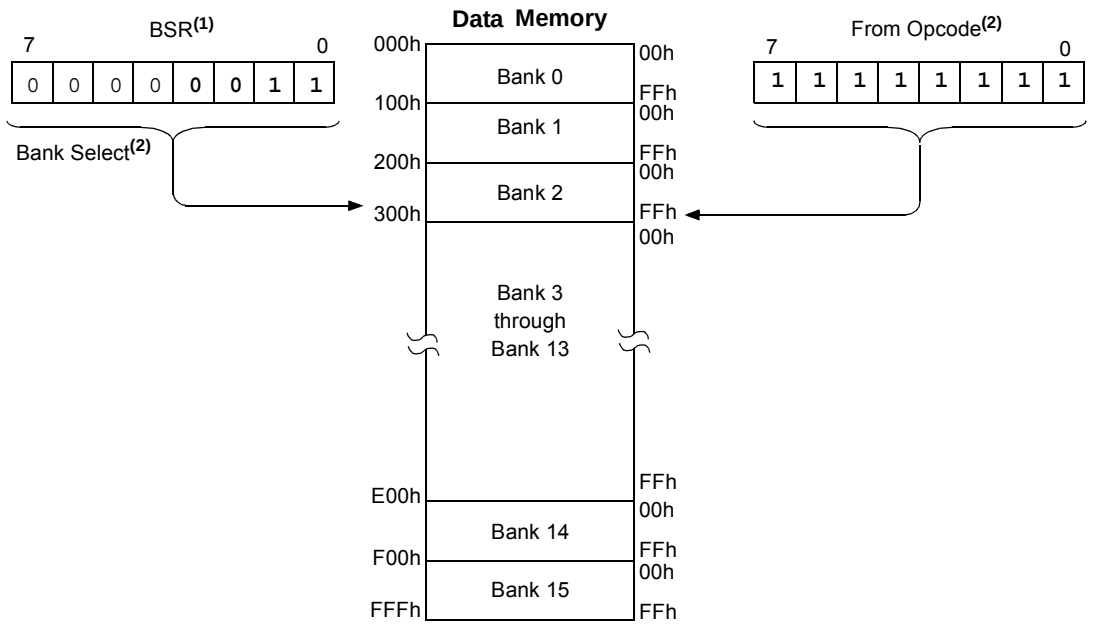


FIGURE 5-7: USE OF THE BANK SELECT REGISTER (DIRECT ADDRESSING)



Note 1: The Access RAM bit of the instruction can be used to force an override of the selected bank (BSR<3:0>) to the registers of the Access Bank.

2: The `MOVFF` instruction embeds the entire 12-bit address in the instruction.

5.3.2 ACCESS BANK

While the use of the BSR with an embedded 8-bit address allows users to address the entire range of data memory, it also means that the user must always ensure that the correct bank is selected. Otherwise, data may be read from or written to the wrong location. This can be disastrous if a GPR is the intended target of an operation, but an SFR is written to instead. Verifying and/or changing the BSR for each read or write to data memory can become very inefficient.

To streamline access for the most commonly used data memory locations, the data memory is configured with an Access Bank, which allows users to access a mapped block of memory without specifying a BSR. The Access Bank consists of the first 128 bytes of memory (00h-7Fh) in Bank 0 and the last 128 bytes of memory (80h-FFh) in Block 15. The lower half is known as the “Access RAM” and is composed of GPRs. This upper half is also where the device’s SFRs are mapped. These two areas are mapped contiguously in the Access Bank and can be addressed in a linear fashion by an 8-bit address (Figure 5-5).

The Access Bank is used by core PIC18 instructions that include the Access RAM bit (the ‘a’ parameter in the instruction). When ‘a’ is equal to ‘`1`’, the instruction uses the BSR and the 8-bit address included in the opcode for the data memory address. When ‘a’ is ‘`0`’, however, the instruction is forced to use the Access Bank address map; the current value of the BSR is ignored entirely.

Using this “forced” addressing allows the instruction to operate on a data address in a single cycle, without updating the BSR first. For 8-bit addresses of 80h and above, this means that users can evaluate and operate on SFRs more efficiently. The Access RAM below 80h is a good place for data values that the user might need to access rapidly, such as immediate computational results or common program variables. Access RAM also allows for faster and more code efficient context saving and switching of variables.

The mapping of the Access Bank is slightly different when the extended instruction set is enabled (XINST Configuration bit = `1`). This is discussed in more detail in **Section 5.5.3 “Mapping the Access Bank in Indexed Literal Offset Mode”**.

5.3.3 GENERAL PURPOSE REGISTER FILE

PIC18 devices may have banked memory in the GPR area. This is data RAM, which is available for use by all instructions. GPRs start at the bottom of Bank 0 (address 000h) and grow upwards towards the bottom of the SFR area. GPRs are not initialized by a Power-on Reset and are unchanged on all other Resets.

REGISTER 9-5: PIR2: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 2

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OSCFIF	CMIF	—	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIF:** Oscillator Fail Interrupt Flag bit
1 = Device oscillator failed, clock input has changed to INTOSC (must be cleared in software)
0 = Device clock operating

bit 6 **CMIF:** Comparator Interrupt Flag bit
1 = Comparator input has changed (must be cleared in software)
0 = Comparator input has not changed

bit 5 **Unimplemented:** Read as '0'

bit 4 **EEIF:** Data EEPROM/Flash Write Operation Interrupt Flag bit
1 = The write operation is complete (must be cleared in software)
0 = The write operation is not complete or has not been started

bit 3 **BCLIF:** Bus Collision Interrupt Flag bit
1 = A bus collision occurred (must be cleared in software)
0 = No bus collision occurred

bit 2 **HLVDIF:** High/Low-Voltage Detect Interrupt Flag bit
1 = A high/low-voltage condition occurred (direction determined by VDIRMAG bit, HLVDCON<7>)
0 = A high/low-voltage condition has not occurred

bit 1 **TMR3IF:** TMR3 Overflow Interrupt Flag bit
1 = TMR3 register overflowed (must be cleared in software)
0 = TMR3 register did not overflow

bit 0 **CCP2IF:** CCP2 Interrupt Flag bit
Capture mode:
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare mode:
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM mode:
Unused in this mode.

TABLE 10-1: PORTA I/O SUMMARY

Pin	Function	TRIS Setting	I/O	I/O Type	Description
RA0/AN0	RA0	0	O	DIG	LATA<0> data output; not affected by analog input.
		1	I	TTL	PORTA<0> data input; disabled when analog input enabled.
	AN0	1	I	ANA	A/D input channel 0 and comparator C1- input. Default input configuration on POR; does not affect digital output.
RA1/AN1	RA1	0	O	DIG	LATA<1> data output; not affected by analog input.
		1	I	TTL	PORTA<1> data input; disabled when analog input enabled.
	AN1	1	I	ANA	A/D input channel 1 and comparator C2- input. Default input configuration on POR; does not affect digital output.
RA2/AN2/ VREF-/CVREF	RA2	0	O	DIG	LATA<2> data output; not affected by analog input. Disabled when CVREF output enabled.
		1	I	TTL	PORTA<2> data input. Disabled when analog functions enabled; disabled when CVREF output enabled.
	AN2	1	I	ANA	A/D input channel 2 and comparator C2+ input. Default input configuration on POR; not affected by analog output.
	VREF-	1	I	ANA	A/D and comparator voltage reference low input.
	CVREF	x	O	ANA	Comparator voltage reference output. Enabling this feature disables digital I/O.
RA3/AN3/VREF+	RA3	0	O	DIG	LATA<3> data output; not affected by analog input.
		1	I	TTL	PORTA<3> data input; disabled when analog input enabled.
	AN3	1	I	ANA	A/D input channel 3 and comparator C1+ input. Default input configuration on POR.
	VREF+	1	I	ANA	A/D and comparator voltage reference high input.
RA4/T0CKI/C1OUT	RA4	0	O	DIG	LATA<4> data output.
		1	I	ST	PORTA<4> data input; default configuration on POR.
	T0CKI	1	I	ST	Timer0 clock input.
	C1OUT	0	O	DIG	Comparator 1 output; takes priority over port data.
RA5/AN4/$\overline{SS}$/ HLVDIN/C2OUT	RA5	0	O	DIG	LATA<5> data output; not affected by analog input.
		1	I	TTL	PORTA<5> data input; disabled when analog input enabled.
	AN4	1	I	ANA	A/D input channel 4. Default configuration on POR.
	$\overline{SS}$	1	I	TTL	Slave select input for MSSP module.
	HLVDIN	1	I	ANA	High/Low-Voltage Detect external trip point input.
	C2OUT	0	O	DIG	Comparator 2 output; takes priority over port data.
OSC2/CLKO/RA6	RA6	0	O	DIG	LATA<6> data output. Enabled in RCIO, INTIO2 and ECIO modes only.
		1	I	TTL	PORTA<6> data input. Enabled in RCIO, INTIO2 and ECIO modes only.
	OSC2	x	O	ANA	Main oscillator feedback output connection (XT, HS and LP modes).
	CLKO	x	O	DIG	System cycle clock output (FOSC/4) in RC, INTIO1 and EC Oscillator modes.
OSC1/CLKI/RA7	RA7	0	O	DIG	LATA<7> data output. Disabled in external oscillator modes.
		1	I	TTL	PORTA<7> data input. Disabled in external oscillator modes.
	OSC1	x	I	ANA	Main oscillator input connection.
	CLKI	x	I	ANA	Main clock input connection.

Legend: DIG = Digital level output; TTL = TTL input buffer; ST = Schmitt Trigger input buffer; ANA = Analog level input/output; x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

REGISTER 10-1: TRISE REGISTER (40/44-PIN DEVICES ONLY)

R-0	R-0	R/W-0	R/W-0	U-0	R/W-1	R/W-1	R/W-1
IBF	OBF	IBOV	PSPMODE	—	TRISE2	TRISE1	TRISE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IBF:** Input Buffer Full Status bit
1 = A word has been received and waiting to be read by the CPU
0 = No word has been received

bit 6 **OBF:** Output Buffer Full Status bit
1 = The output buffer still holds a previously written word
0 = The output buffer has been read

bit 5 **IBOV:** Input Buffer Overflow Detect bit (in Microprocessor mode)
1 = A write occurred when a previously input word has not been read (must be cleared in software)
0 = No overflow occurred

bit 4 **PSPMODE:** Parallel Slave Port Mode Select bit
1 = Parallel Slave Port mode
0 = General purpose I/O mode

bit 3 **Unimplemented:** Read as '0'

bit 2 **TRISE2:** RE2 Direction Control bit
1 = Input
0 = Output

bit 1 **TRISE1:** RE1 Direction Control bit
1 = Input
0 = Output

bit 0 **TRISE0:** RE0 Direction Control bit
1 = Input
0 = Output

15.0 CAPTURE/COMPARE/PWM (CCP) MODULES

PIC18F2420/2520/4420/4520 devices all have two CCP (Capture/Compare/PWM) modules. Each module contains a 16-bit register which can operate as a 16-bit Capture register, a 16-bit Compare register or a PWM Master/Slave Duty Cycle register.

In 28-pin devices, the two standard CCP modules (CCP1 and CCP2) operate as described in this chapter. In 40/44-pin devices, CCP1 is implemented as an Enhanced CCP module with standard Capture and Compare modes and Enhanced PWM modes. The ECCP implementation is discussed in **Section 16.0 "Enhanced Capture/Compare/PWM (ECCP) Module"**.

The capture and compare operations described in this chapter apply to all standard and Enhanced CCP modules.

Note: Throughout this section and **Section 16.0 "Enhanced Capture/Compare/PWM (ECCP) Module"**, references to the register and bit names for CCP modules are referred to generically by the use of 'x' or 'y' in place of the specific module number. Thus, "CCPxCON" might refer to the control register for CCP1, CCP2 or ECCP1. "CCPxCON" is used throughout these sections to refer to the module control register, regardless of whether the CCP module is a standard or enhanced implementation.

REGISTER 15-1: CCPxCON: CCPx CONTROL REGISTER (28-PIN DEVICES)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DCxB1	DCxB0	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DCxB<1:0>:** PWM Duty Cycle bit 1 and bit 0 for CCPx Module

Capture mode:
Unused.

Compare mode:
Unused.

PWM mode:
These bits are the two LSbs (bit 1 and bit 0) of the 10-bit PWM duty cycle. The eight MSbs (DCxB<9:2>) of the duty cycle are found in CCPRxL.

bit 3-0 **CCPxM<3:0>:** CCPx Module Mode Select bits

0000 = Capture/Compare/PWM disabled (resets CCPx module)
0001 = Reserved
0010 = Compare mode, toggle output on match (CCPxIF bit is set)
0011 = Reserved
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode, initialize CCPx pin low; on compare match, force CCPx pin high (CCPxIF bit is set)
1001 = Compare mode, initialize CCPx pin high; on compare match, force CCPx pin low (CCPxIF bit is set)
1010 = Compare mode, generate software interrupt on compare match (CCPxIF bit is set, CCPx pin reflects I/O state)
1011 = Compare mode, trigger special event; reset timer; CCP2 match starts A/D conversion (CCPxIF bit is set)
11xx = PWM mode

17.4 I²C Mode

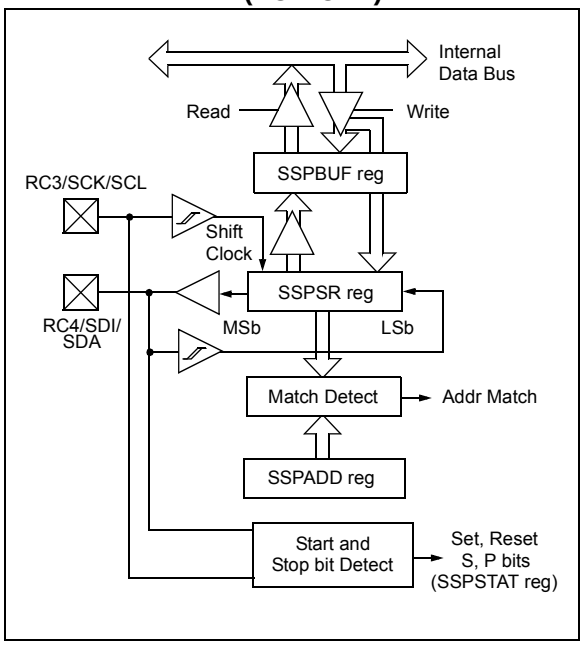
The MSSP module in I²C mode fully implements all master and slave functions (including general call support) and provides interrupts on Start and Stop bits in hardware to determine a free bus (multi-master function). The MSSP module implements the standard mode specifications, as well as 7-Bit and 10-Bit Addressing modes.

Two pins are used for data transfer:

- Serial clock (SCL) – RC3/SCK/SCL
- Serial data (SDA) – RC4/SDI/SDA

The user must configure these pins as inputs or outputs through the TRISC<4:3> bits.

FIGURE 17-7: MSSP BLOCK DIAGRAM (I²C MODE)



17.4.1 REGISTERS

The MSSP module has six registers for I²C operation. These are:

- MSSP Control Register 1 (SSPCON1)
- MSSP Control Register 2 (SSPCON2)
- MSSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer Register (SSPBUF)
- MSSP Shift Register (SSPSR) – Not directly accessible
- MSSP Address Register (SSPADD)

SSPCON1, SSPCON2 and SSPSTAT are the control and status registers in I²C mode operation. The SSPCON1 and SSPCON2 registers are readable and writable. The lower 6 bits of the SSPSTAT are read-only. The upper two bits of the SSPSTAT are read/write.

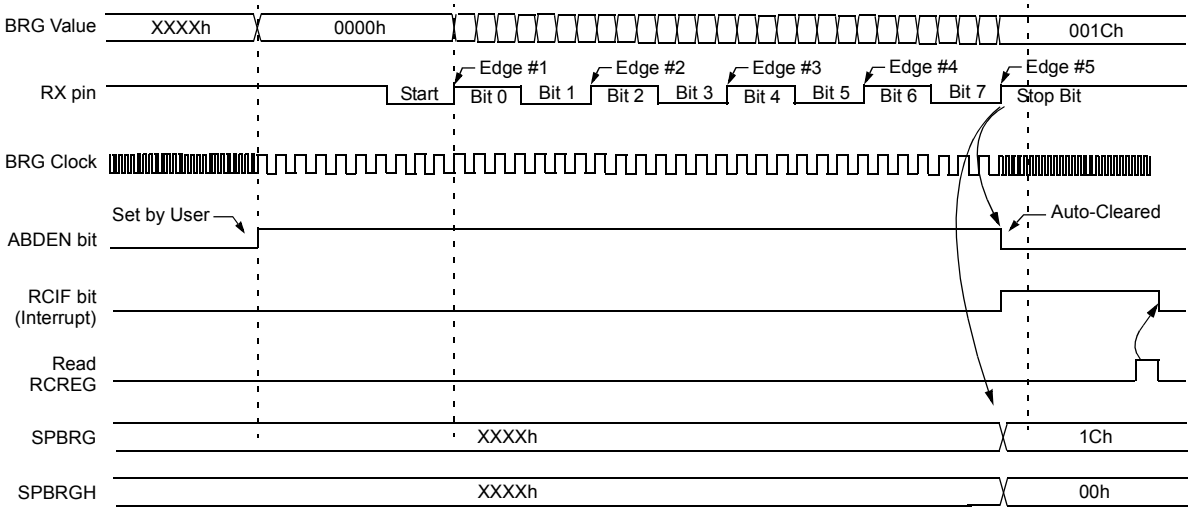
SSPSR is the shift register used for shifting data in or out. SSPBUF is the buffer register to which data bytes are written to or read from.

SSPADD register holds the slave device address when the MSSP is configured in I²C Slave mode. When the MSSP is configured in Master mode, the lower seven bits of SSPADD act as the Baud Rate Generator reload value.

In receive operations, SSPSR and SSPBUF together create a double-buffered receiver. When SSPSR receives a complete byte, it is transferred to SSPBUF and the SSPIF interrupt is set.

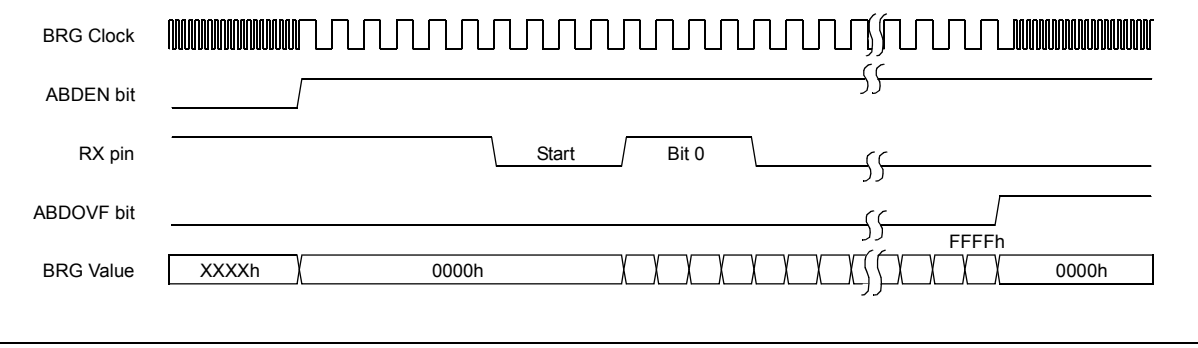
During transmission, the SSPBUF is not double-buffered. A write to SSPBUF will write to both SSPBUF and SSPSR.

FIGURE 18-1: AUTOMATIC BAUD RATE CALCULATION



Note: The ABD sequence requires the EUSART module to be configured in Asynchronous mode and WUE = 0.

FIGURE 18-2: BRG OVERFLOW SEQUENCE



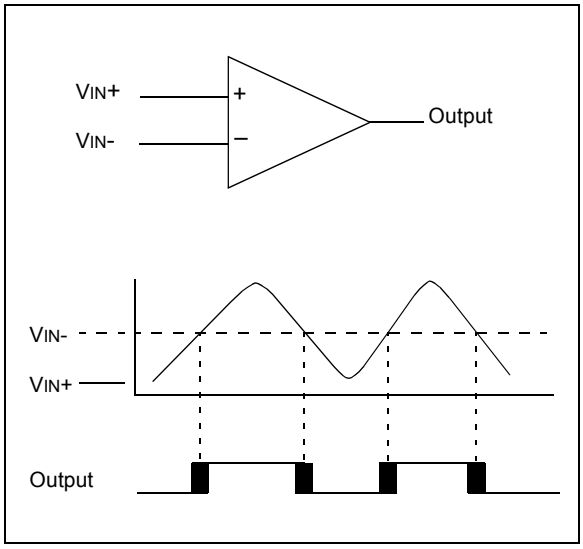
20.2 Comparator Operation

A single comparator is shown in Figure 20-2, along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 20-2 represent the uncertainty, due to input offsets and response time.

20.3 Comparator Reference

Depending on the comparator operating mode, either an external or internal voltage reference may be used. The analog signal present at VIN- is compared to the signal at VIN+ and the digital output of the comparator is adjusted accordingly (Figure 20-2).

FIGURE 20-2: SINGLE COMPARATOR



20.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSS and VDD and can be applied to either pin of the comparator(s).

20.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference from the comparator voltage reference module. This module is described in more detail in **Section 21.0 "Comparator Voltage Reference Module"**.

The internal reference is only available in the mode where four inputs are multiplexed to two comparators (CM<2:0> = 110). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

20.4 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output has a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs. Otherwise, the maximum delay of the comparators should be used (see **Section 26.0 "Electrical Characteristics"**).

20.5 Comparator Outputs

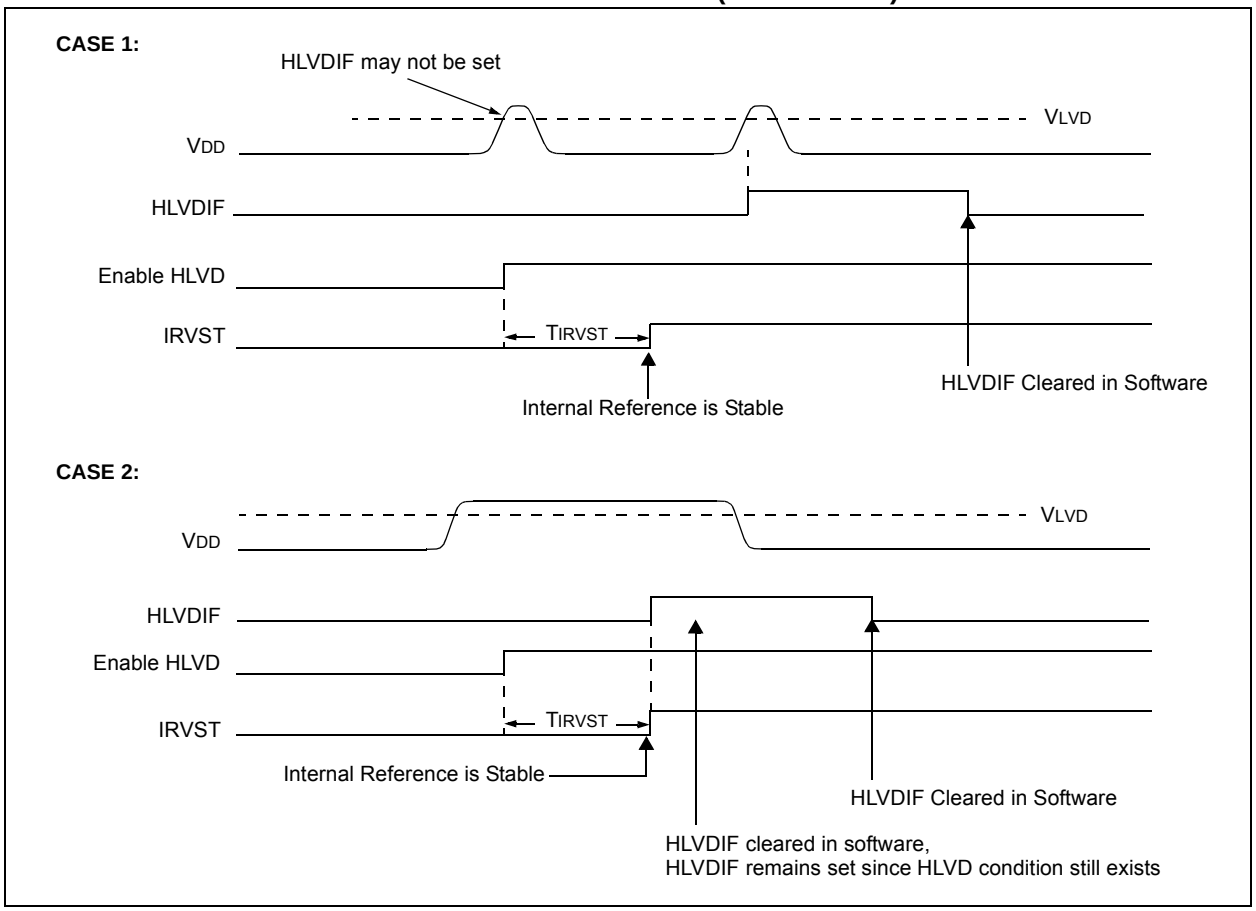
The comparator outputs are read through the CMCON register. These bits are read-only. The comparator outputs may also be directly output to the RA4 and RA5 I/O pins. When enabled, multiplexers in the output path of the RA4 and RA5 pins will switch and the output of each pin will be the unsynchronized output of the comparator. The uncertainty of each of the comparators is related to the input offset voltage and the response time given in the specifications. Figure 20-3 shows the comparator output block diagram.

The TRISA bits will still function as an output enable/ disable for the RA4 and RA5 pins while in this mode.

The polarity of the comparator outputs can be changed using the C2INV and C1INV bits (CMCON<4:5>).

Note 1:	When reading the PORT register, all pins configured as analog inputs will read as '0'. Pins configured as digital inputs will convert an analog input according to the Schmitt Trigger input specification.
2:	Analog levels on any pin defined as a digital input may cause the input buffer to consume more current than is specified.

FIGURE 22-3: HIGH-VOLTAGE DETECT OPERATION (VDIRMAG = 1)

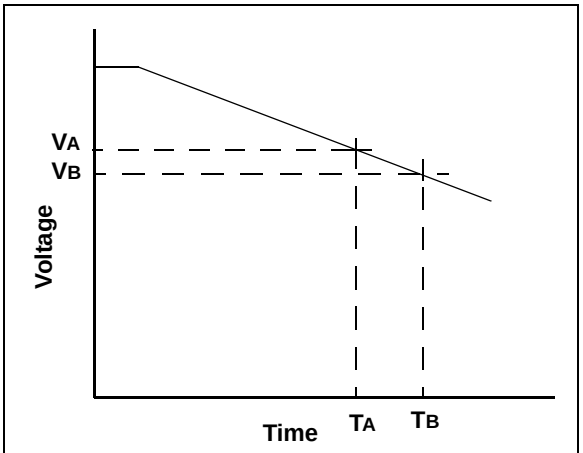


22.5 Applications

In many applications, the ability to detect a drop below, or rise above, a particular threshold is desirable. For example, the HLVD module could be periodically enabled to detect Universal Serial Bus (USB) attach or detach. This assumes the device is powered by a lower voltage source than the USB when detached. An attach would indicate a high-voltage detect from, for example, 3.3V to 5V (the voltage on USB) and vice versa for a detach. This feature could save a design a few extra components and an attach signal (input pin).

For general battery applications, Figure 22-4 shows a possible voltage curve. Over time, the device voltage decreases. When the device voltage reaches voltage, VA, the HLVD logic generates an interrupt at time, TA. The interrupt could cause the execution of an ISR, which would allow the application to perform "housekeeping tasks" and perform a controlled shutdown before the device voltage exits the valid operating range at TB. The HLVD, thus, would give the application a time window, represented by the difference between TA and TB, to safely exit.

FIGURE 22-4: TYPICAL LOW-VOLTAGE DETECT APPLICATION



Legend: VA = HLVD trip point
VB = Minimum valid device operating voltage

23.0 SPECIAL FEATURES OF THE CPU

PIC18F2420/2520/4420/4520 devices include several features intended to maximize reliability and minimize cost through elimination of external components. These are:

- Oscillator Selection
- Resets:
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- Fail-Safe Clock Monitor
- Two-Speed Start-up
- Code Protection
- ID Locations
- In-Circuit Serial Programming

The oscillator can be configured for the application depending on frequency, power, accuracy and cost. All of the options are discussed in detail in **Section 2.0 "Oscillator Configurations"**.

A complete discussion of device Resets and interrupts is available in previous sections of this data sheet.

In addition to their Power-up and Oscillator Start-up Timers provided for Resets, PIC18F2420/2520/4420/4520 devices have a Watchdog Timer, which is either permanently enabled via the Configuration bits or software controlled (if configured as disabled).

The inclusion of an internal RC oscillator also provides the additional benefits of a Fail-Safe Clock Monitor (FSCM) and Two-Speed Start-up. FSCM provides for background monitoring of the peripheral clock and automatic switchover in the event of its failure. Two-Speed Start-up enables code to be executed almost immediately on start-up, while the primary clock source completes its start-up delays.

All of these features are enabled and configured by setting the appropriate Configuration register bits.

23.1 Configuration Bits

The Configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped starting at program memory location, 300000h.

The user will note that address 300000h is beyond the user program memory space. In fact, it belongs to the configuration memory space (300000h-3FFFFFh), which can only be accessed using table reads and table writes.

Programming the Configuration registers is done in a manner similar to programming the Flash memory. The WR bit in the EECON1 register starts a self-timed write to the Configuration register. In normal operation mode, a TBLWT instruction with the TBLPTR pointing to the Configuration register sets up the address and the data for the Configuration register write. Setting the WR bit starts a long write to the Configuration register. The Configuration registers are written a byte at a time. To write or erase a configuration cell, a TBLWT instruction can write a '1' or a '0' into the cell. For additional details on Flash programming, refer to **Section 6.5 "Writing to Flash Program Memory"**.

TABLE 23-1: CONFIGURATION BITS AND DEVICE IDs

File Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value
300001h	CONFIG1H	IESO	FCMEN	—	—	FOSC3	FOSC2	FOSC1	FOSC0	00-- 0111
300002h	CONFIG2L	—	—	—	BORV1	BORV0	BOREN1	BOREN0	$\overline{\text{PWRTEN}}$	---1 1111
300003h	CONFIG2H	—	—	—	WDTPS3	WDTPS2	WDTPS1	WDTPS0	WDTEN	---1 1111
300005h	CONFIG3H	MCLRE	—	—	—	—	LPT1OSC	PBADEN	CCP2MX	1--- -011
300006h	CONFIG4L	$\overline{\text{DEBUG}}$	XINST	—	—	—	LVP	—	STVREN	10-- -1-1
300008h	CONFIG5L	—	—	—	—	CP3(1)	CP2(1)	CP1	CP0	---- 1111
300009h	CONFIG5H	CPD	CPB	—	—	—	—	—	—	11-- ----
30000Ah	CONFIG6L	—	—	—	—	WRT3(1)	WRT2(1)	WRT1	WRT0	---- 1111
30000Bh	CONFIG6H	WRTD	WRTB	WRTC	—	—	—	—	—	111- ----
30000Ch	CONFIG7L	—	—	—	—	EBTR3(1)	EBTR2(1)	EBTR1	EBTR0	---- 1111
30000Dh	CONFIG7H	—	EBTRB	—	—	—	—	—	—	-1-- ----
3FFFFEh	DEVID1	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	xxxx xxxx(2)
3FFFFFh	DEVID2	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	xxxx xxxx(2)

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition.
Shaded cells are unimplemented, read as '0'.

Note 1: Unimplemented in PIC18F2420/4420 devices; maintain this bit set.

2: See Register 23-12 for DEVID1 values. DEVID registers are read-only and cannot be programmed by the user.

MOVFF **Move f to f**

Syntax: MOVFF f_s,f_d

Operands: $0 \le f_s \le 4095$
$0 \le f_d \le 4095$

Operation: $(f_s) \rightarrow f_d$

Status Affected: None

Encoding:

1st word (source)	1100	ffff	ffff	$ffff_s$
2nd word (destin.)	1111	ffff	ffff	$ffff_d$

Description: The contents of source register 'f_s' are moved to destination register 'f_d'. Location of source 'f_s' can be anywhere in the 4096-byte data space (000h to FFFh) and location of destination 'f_d' can also be anywhere from 000h to FFFh.
Either source or destination can be W (a useful special situation).
MOVFF is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port).
The MOVFF instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.

Words: 2

Cycles: 2 (3)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f' (src)	Process Data	No operation
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

Example: MOVFF REG1, REG2

Before Instruction
REG1 = 33h
REG2 = 11h
After Instruction
REG1 = 33h
REG2 = 33h

MOVLB **Move Literal to Low Nibble in BSR**

Syntax: MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow$ BSR

Status Affected: None

Encoding:

0000	0001	kkkk	kkkk

Description: The 8-bit literal 'k' is loaded into the Bank Select Register (BSR). The value of BSR<7:4> always remains '0', regardless of the value of k_7:k_4.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write literal 'k' to BSR

Example: MOVLB 5

Before Instruction
BSR Register = 02h
After Instruction
BSR Register = 05h

MULLW **Multiply Literal with W**

Syntax: MULLW k

Operands: $0 \le k \le 255$

Operation: (W) x k → PRODH:PRODL

Status Affected: None

Encoding:

0000	1101	kkkk	kkkk

Description: An unsigned multiplication is carried out between the contents of W and the 8-bit literal 'k'. The 16-bit result is placed in the PRODH:PRODL register pair. PRODH contains the high byte. W is unchanged.
None of the Status flags are affected. Note that neither Overflow nor Carry is possible in this operation. A zero result is possible but not detected.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write registers PRODH: PRODL

Example: MULLW 0C4h

Before Instruction
W = E2h
PRODH = ?
PRODL = ?
After Instruction
W = E2h
PRODH = ADh
PRODL = 08h

MULWF **Multiply W with f**

Syntax: MULWF f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (W) x (f) → PRODH:PRODL

Status Affected: None

Encoding:

0000	001a	ffff	ffff

Description: An unsigned multiplication is carried out between the contents of W and the register file location 'f'. The 16-bit result is stored in the PRODH:PRODL register pair. PRODH contains the high byte. Both W and 'f' are unchanged.
None of the Status flags are affected. Note that neither Overflow nor Carry is possible in this operation. A zero result is possible but not detected.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write registers PRODH: PRODL

Example: MULWF REG, 1

Before Instruction
W = C4h
REG = B5h
PRODH = ?
PRODL = ?
After Instruction
W = C4h
REG = B5h
PRODH = 8Ah
PRODL = 94h

24.2.5 SPECIAL CONSIDERATIONS WITH MICROCHIP MPLAB® IDE TOOLS

The latest versions of Microchip's software tools have been designed to fully support the extended instruction set of the PIC18F2420/2520/4420/4520 family of devices. This includes the MPLAB C18 C compiler, MPASM assembly language and MPLAB Integrated Development Environment (IDE).

When selecting a target device for software development, MPLAB IDE will automatically set default Configuration bits for that device. The default setting for the XINST Configuration bit is '0', disabling the extended instruction set and Indexed Literal Offset Addressing mode. For proper execution of applications developed to take advantage of the extended instruction set, XINST must be set during programming.

To develop software for the extended instruction set, the user must enable support for the instructions and the Indexed Addressing mode in their language tool(s). Depending on the environment being used, this may be done in several ways:

- A menu option, or dialog box within the environment, that allows the user to configure the language tool and its settings for the project
- A command line option
- A directive in the source code

These options vary between different compilers, assemblers and development environments. Users are encouraged to review the documentation accompanying their development systems for the appropriate information.

26.4.2 TIMING CONDITIONS

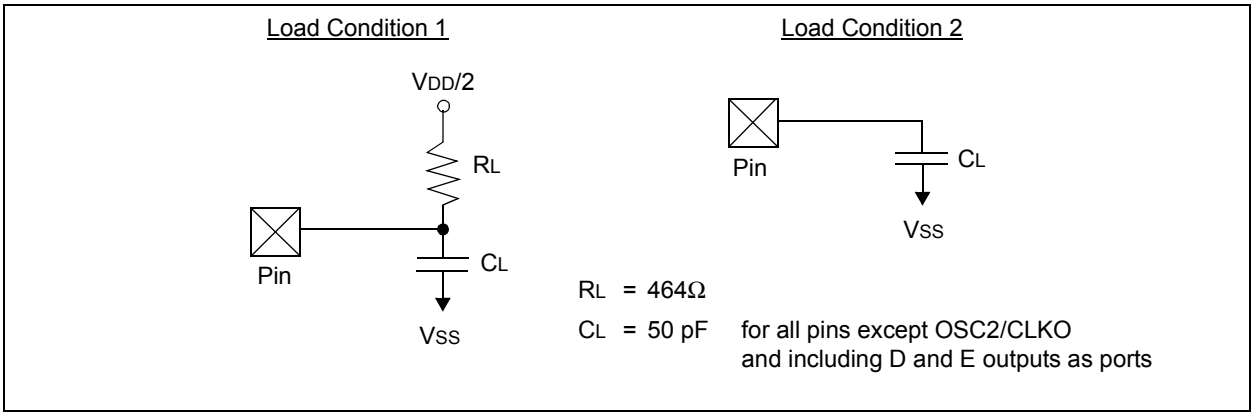
The temperature and voltages specified in Table 26-5 apply to all timing specifications unless otherwise noted. Figure 26-5 specifies the load conditions for the timing specifications.

Note:	Because of space limitations, the generic terms “PIC18FXXXX” and “PIC18LFXXXX” are used throughout this section to refer to the PIC18F2420/2520/4420/4520 and PIC18LF2420/2520/4420/4520 families of devices specifically and only those devices.

TABLE 26-5: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial Operating voltage VDD range as described in DC specification **Section 26.1** and **Section 26.3**. LF parts operate for industrial temperatures only.

FIGURE 26-5: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



26.4.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 26-6: EXTERNAL CLOCK TIMING (ALL MODES EXCEPT PLL)

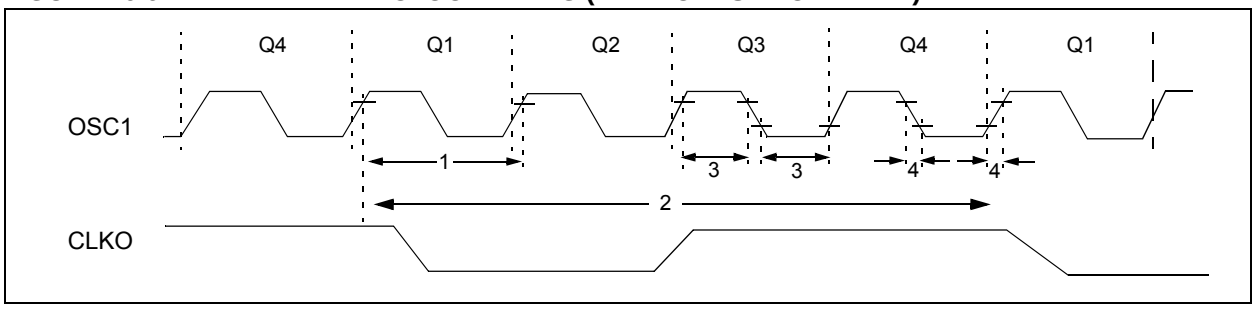


TABLE 26-6: EXTERNAL CLOCK TIMING REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
1A	FOSC	External CLKI Frequency(1)	DC	1	MHz	XT, RC Oscillator mode
			DC	25	MHz	HS Oscillator mode
			DC	31.25	kHz	LP Oscillator mode
			DC	40	MHz	EC Oscillator mode
		Oscillator Frequency(1)	DC	4	MHz	RC Oscillator mode
			0.1	4	MHz	XT Oscillator mode
			4	25	MHz	HS Oscillator mode
			4	10	MHz	HS + PLL Oscillator mode
			5	200	kHz	LP Oscillator mode
1	TOSC	External CLKI Period(1)	1000	—	ns	XT, RC Oscillator mode
			40	—	ns	HS Oscillator mode
			32	—	µs	LP Oscillator mode
			25	—	ns	EC Oscillator mode
		Oscillator Period(1)	250	—	ns	RC Oscillator mode
			0.25	10	µs	XT Oscillator mode
			40	250	ns	HS Oscillator mode
			100	250	ns	HS + PLL Oscillator mode
			5	200	µs	LP Oscillator mode
2	TCY	Instruction Cycle Time(1)	100	—	ns	TCY = 4/FOSC, Industrial
			160	—	ns	TCY = 4/FOSC, Extended
3	TOSL, TOSH	External Clock in (OSC1) High or Low Time	30	—	ns	XT Oscillator mode
			2.5	—	µs	LP Oscillator mode
			10	—	ns	HS Oscillator mode
4	TOSR, TOSF	External Clock in (OSC1) Rise or Fall Time	—	20	ns	XT Oscillator mode
			—	50	ns	LP Oscillator mode
			—	7.5	ns	HS Oscillator mode

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period for all configurations except PLL. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

TABLE 26-19: I²C™ BUS DATA REQUIREMENTS (SLAVE MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	µs	
			400 kHz mode	0.6	—	µs	
			MSSP module	1.5 TCY	—		
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			MSSP module	1.5 TCY	—		
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

INDEX